



Material Content Data Sheet



Sales Product Name		BTT6200-4EMA		Issued		25. January 2018		
MA#		MA001411870						
Package		PG-SSOP-24-14		Weight*		151.82 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.840	1.87	1.87	18706	18706
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		112	
	non noble metal	zinc	7440-66-6	0.068	0.04		446	
	non noble metal	iron	7439-89-6	1.355	0.89		8922	
	non noble metal	copper	7440-50-8	54.998	36.23	37.17	362268	371748
wire	non noble metal	copper	7440-50-8	0.627	0.41	0.41	4132	4132
encapsulation	organic material	carbon black	1333-86-4	0.173	0.11		1142	
	plastics	epoxy resin	-	7.976	5.25		52537	
	inorganic material	silicondioxide	60676-86-0	78.546	51.75	57.11	517371	571050
leadfinish	non noble metal	tin	7440-31-5	2.911	1.92	1.92	19174	19174
plating	noble metal	silver	7440-22-4	1.379	0.91	0.91	9085	9085
glue	plastics	epoxy resin	-	0.162	0.11		1068	
	noble metal	silver	7440-22-4	0.765	0.50	0.61	5037	6105
*deviation	< 10%				Sum in total:		100.00	1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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